

## **SSC8415GS6B**

#### P-Channel Enhancement Mode MOSFET

#### > Features

V <sub>DS</sub>	V <sub>GS</sub>	R <sub>DS(ON)</sub> Typ.	ID
-20V	±12V	41mΩ @-4V5	-3.7A
		54mΩ @-2V5	-5.77

## > Description

This device is produced with high cell density DMOS trench technology, which is especially used to minimize on-state resistance. This device particularly suits low voltage applications such as portable equipment, power management and other battery powered circuits, and low in-line power dissipation are needed in a very small outline surface mount package.

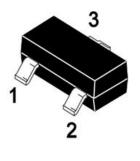
## Applications

- Load Switch
- Portable Devices
- DCDC Conversion

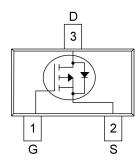
## Ordering Information

Device	Package	Shipping
SSC8415GS6B	SOT-23	3000/Reel

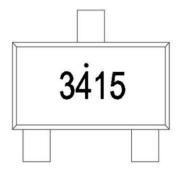
## Pin configuration



**SOT-23** 



Pin Configuration (Top View)



**Marking** 



## ➤ Absolute Maximum Ratings (T<sub>A</sub>=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Unit
V <sub>DSS</sub>	Drain-to-Source Voltage	-20	V
V <sub>GSS</sub>	Gate-to-Source Voltage	±12	V
I <sub>D</sub>	Continuous Drain Current <sup>a</sup>	-3.7	Α
I <sub>DM</sub>	Pulsed Drain Current <sup>b</sup>	-15	Α
P <sub>D</sub>	Power Dissipation <sup>c</sup>	0.9	W
TJ	Operation junction temperature	-55 to 150	$^{\circ}$
T <sub>STG</sub>	Storage temperature range	-55 to 150	$^{\circ}$

## $\triangleright$ Thermal Resistance Ratings (T<sub>A</sub>=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance <sup>a</sup>	140	°C/W

#### Note:

- a. The value of R<sub>θJA</sub> is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with T<sub>A</sub>=25 °C. The value in any given application depends on the user is specific board design. The power dissipation is based on the t≤10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation  $P_D$  is based on  $T_{J(MAX)}$ =150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

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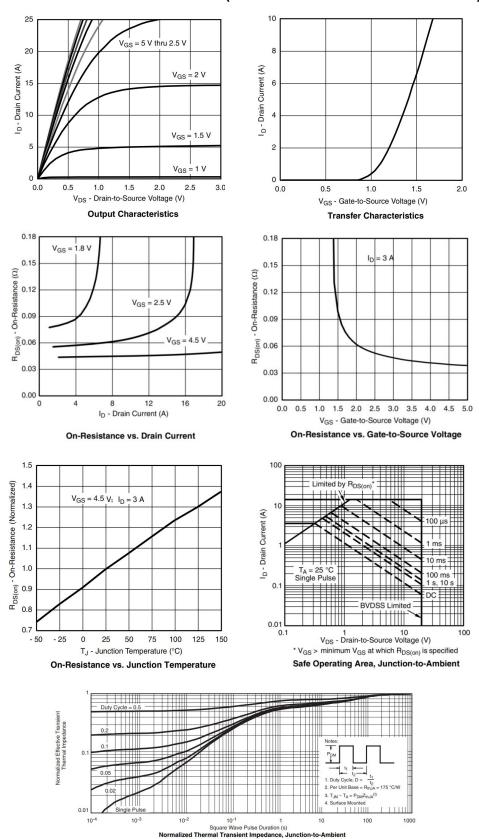


# ➤ Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V <sub>GS</sub> =0V, I <sub>D</sub> =-10uA	-20			V
Gate Threshold Voltage	$V_{GS(th)}$	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250uA	-0.4	-0.6	-1	V
Drain Source On Registence	R <sub>DS(on)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-3.5A		41	53	mΩ
Drain-Source On-Resistance		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-3A		54	70	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V			-1	μA
Gate-Source Leak Current	I <sub>GSS</sub>	V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V			±100	nA
Forward Voltage	$V_{\text{SD}}$	V <sub>GS</sub> =0V, I <sub>S</sub> =-1.6A	-0.5	-0.75	-1.2	V
Input Capacitance	C <sub>ISS</sub>			869		pF
Output Capacitance	Coss	$V_{DS} = -10V$ , $V_{GS} = 0V$ , $f = 1MHz$		265		
Reverse Transfer Capacitance	C <sub>RSS</sub>			258		
Turn-on Delay Time	$T_{D(ON)}$			12		- ns
Rise Time	Tr	$V_{DS}$ =10V, $I_{D}$ =-1.0A, $R_{L}$ =6 $\Omega$ , $V_{GS}$ =-4.5V, $R_{G}$ =6 $\Omega$ ,		8.9		
Turn-off Delay Time	$T_{D(OFF)}$			45		
Fall Time	$T_f$			15		
Total Gate Charge	$Q_{G}$			12		
Gate to Source Charge	$Q_GS$	V <sub>DS</sub> =-10V , V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-5A		2.1		nC
Gate to Drain Charge	Q <sub>GD</sub>			2.4		

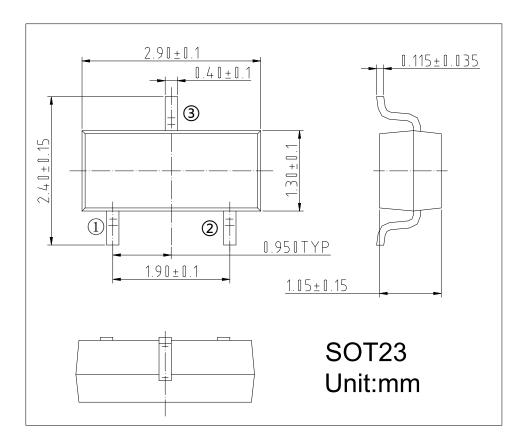


# $\succ$ Typical Performance Characteristics (T<sub>A</sub>=25 $^{\circ}$ C unless otherwise noted)

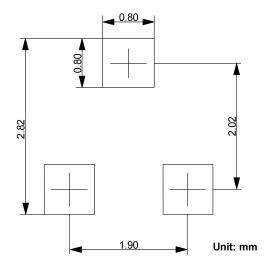




# Package Information



#### > Recommended Pad outline





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